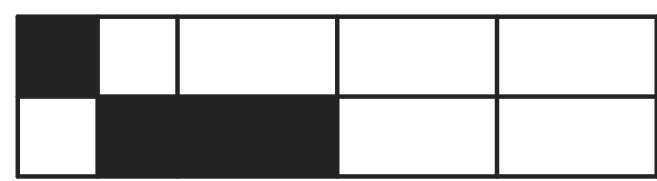
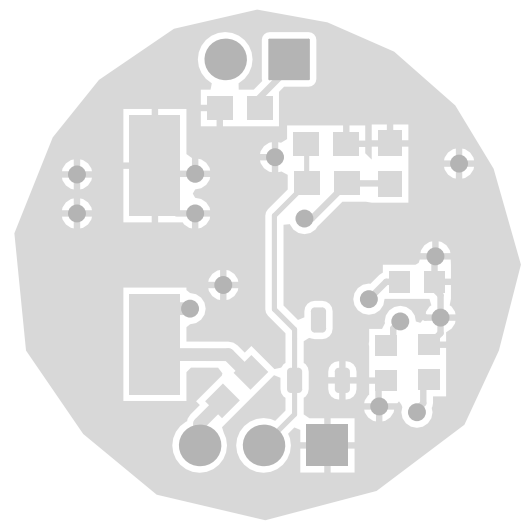


← 999.91mil →



← 1000.00mil →

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01597	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01597		
PLOT NAME = Top Layer	GENERATED : 1/3/2018	1:22:23 PM	TEXAS INSTRUMENTS



← 999.91mil →



← 1000.00mil →

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01597	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01597		
PLOT NAME = Bottom Layer	GENERATED : 1/3/2018 1:22:27 PM	TEXAS INSTRUMENTS	

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